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Acceleration of Deep Learning using Intel® Distribution of OpenVINO™ toolkit: 3D Seismic Case Study

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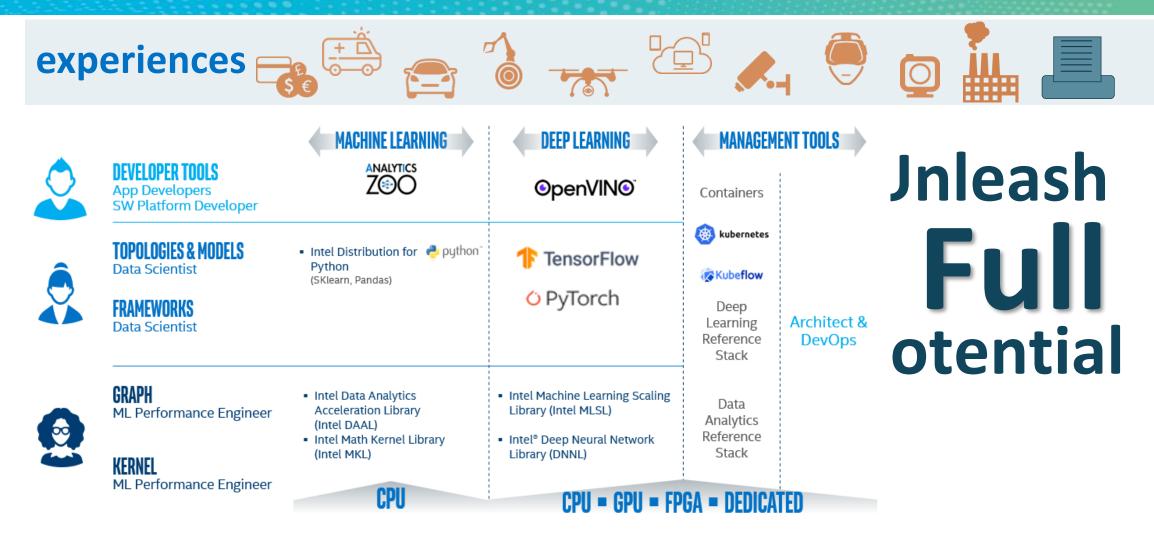
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Combine SW & HW for Full Potential



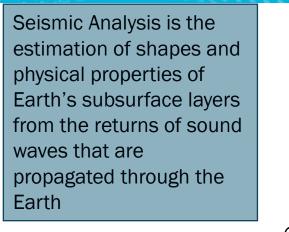


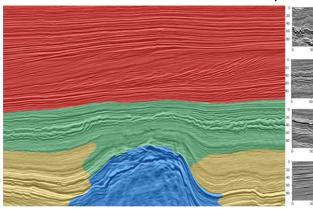


Pain Point in Seismic Analysis — Data Movement

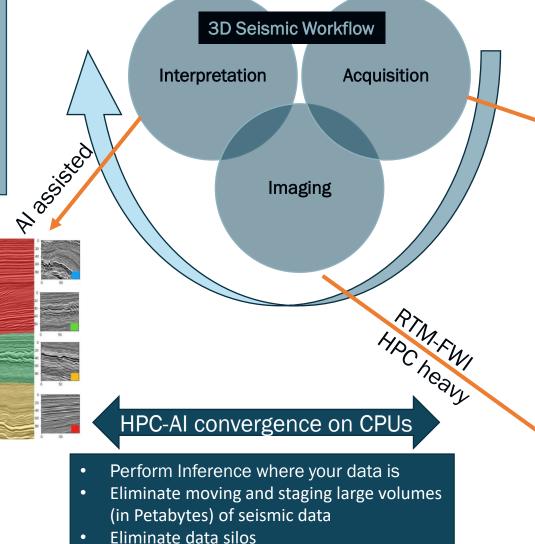
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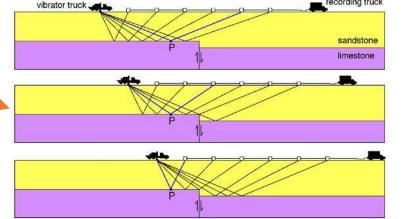
recording truck



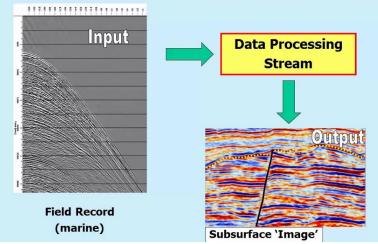


https://www.enthought.com/





Source: https://www.oilandgaslawyerblog.com/



Accelerate Performance for Deep Learning Inference for 3D Seismic



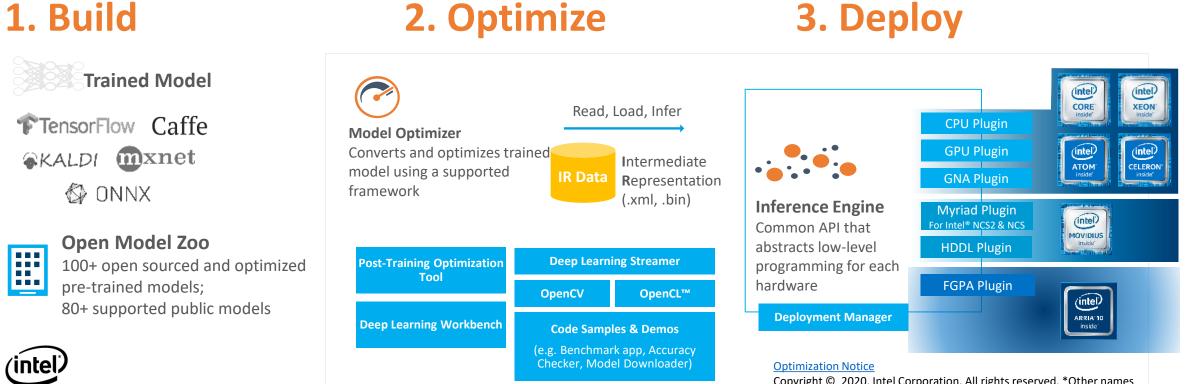
Objective: General purpose Intel[®] Xeon[®] can be used for both HPC and AI workloads in oil and gas – show optimization in AI pipeline

- Full stack solution: Increase performance of DL models for oil & gas datasets on Intel[®] Xeon[®] processor using Intel[®] Distribution of OpenVINO[™] toolkit
- A well-cited 3D seismic use-case was used to show this performance boost



Tool Suite for High-Performance, Deep Learning Inference

Faster, more accurate real-world results using high-performance, AI and computer vision inference deployed into production across Intel[®] architecture from edge to cloud



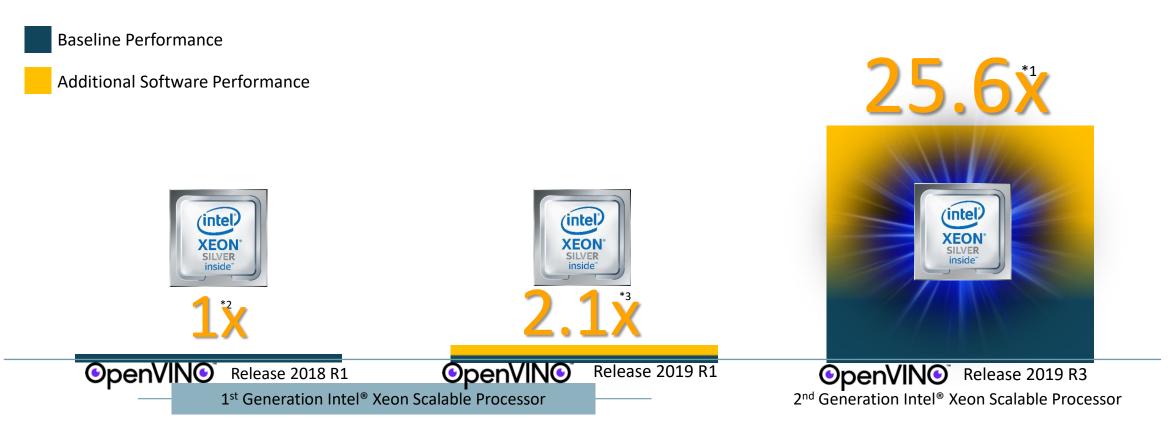
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Improvements Means Exponential Performance



For more complete information about performance and benchmark results, visit <u>www.intel.com/benchmarks</u>. See backup for configuration details. Comparison of Frames Per Second utilizing Mobilenet SSD, Batch 1.



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Powered by the Intel[®] Distribution of OpenVINO[™] toolkit

Improvements made by pairing together Intel[®] architecture-based systems and deep learning acceleration powered by the Intel[®] Distribution of OpenVINO[™] toolkit

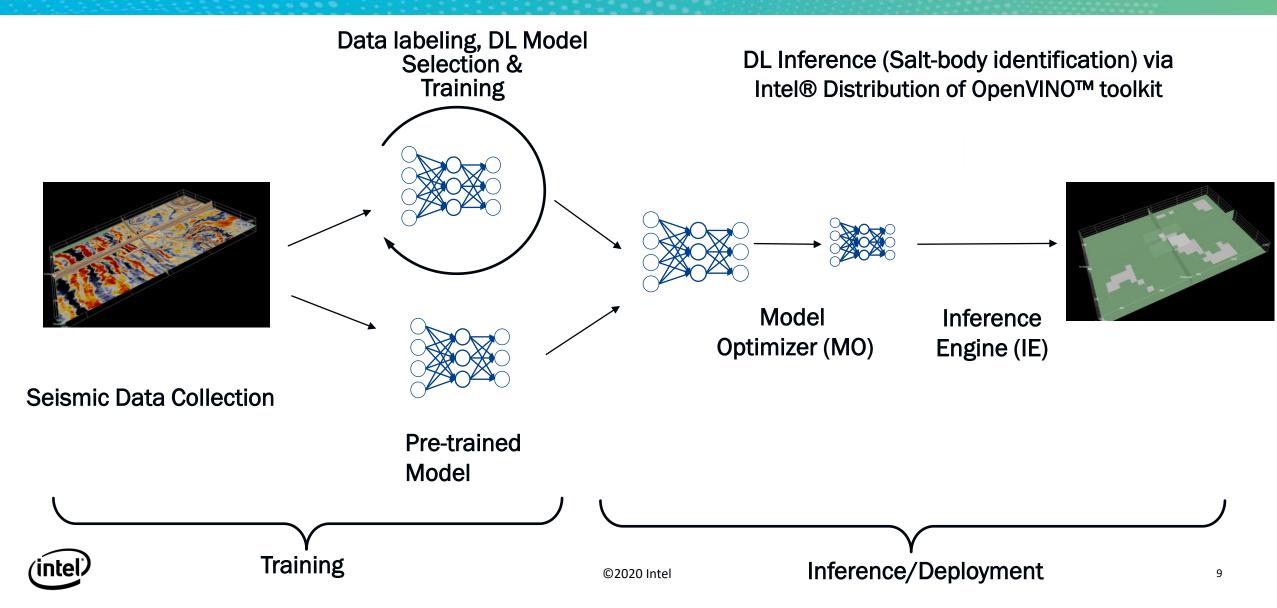




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Deep Learning Seismic Workflow

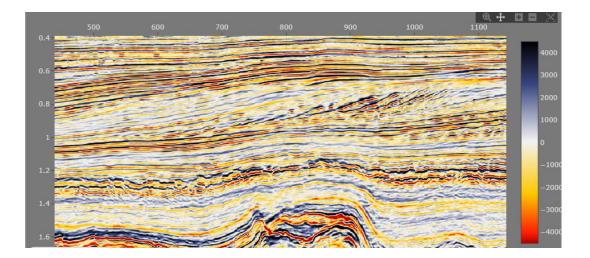




Use-case: Salt Identification in 3D Seismic

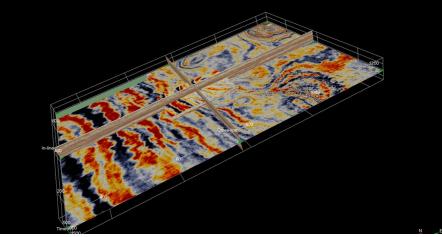


- Data used
 - 3D seismic data of F3 Dutch block

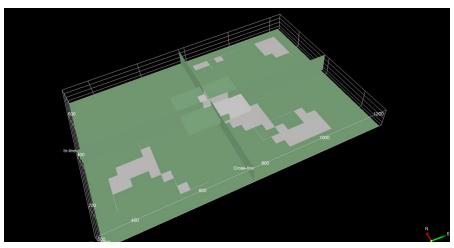


Source: dGB

- Model used
 - CNN for ASI by Waldeland, 2018*



Original F3 3D-seismic section







*Convolutional neural networks for automated seismic interpretation, Anders U. Waldeland, Are Charles Jensen, Leiv-J. Gelius, and Anne H. Schistad Solberg, The Leading Edge 2018 37:7, 529-537

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Why Salt?



Why Salts are important:

- Salt-bodies are important subsurface structures with significant implications for hydrocarbon accumulation and sealing in offshore petroleum reservoirs
- If Salts are not recognized prior to drilling, they can lead to number of complications if encountered unexpectedly while drilling the well

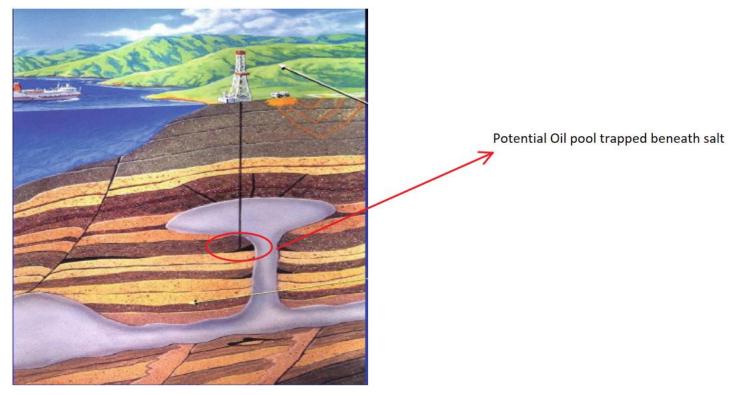
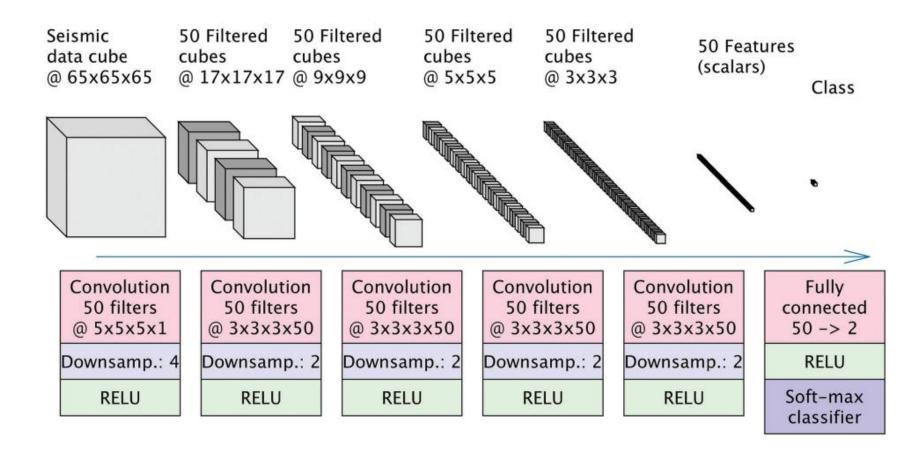


Figure is modified from: https://www.sciencedirect.com/topics/earth-and-planetary-sciences/salt-dome



Salt Identification CNN Model*





The full 3D cube is partitioned into smaller mini cubes of $65 \times 65 \times 65$ samples, which are input into the network – to predict the class of the center pixel

*Convolutional neural networks for automated seismic interpretation, Anders U. Waldeland, Are Charles Jensen, Leiv-J. Gelius, and Anne H. Schistad Solberg, The Leading Edge 2018 37:7, 529-537



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Performance Result



CNN model	System type	OpenVINO™ used (base model)	Inference time* (ms)	Numerical difference in accuracy between OpenVINO [™] and base model
5 layers of 3D	Intel Xeon Gold 6252 CPU @ 2.10 GHz (24	No (PyTorch)	70.20	
convolutions (PyTorch model)	cores)	Yes	4.14	1.1445E-05

*Inference time for one 65*65*65 cube

- Intel[®] Distribution of OpenVINO[™] toolkit provides over 15X boost on 2nd generation Xeons
 Data used: 1 Gb 3D seismic data of
- Details of benchmarking:

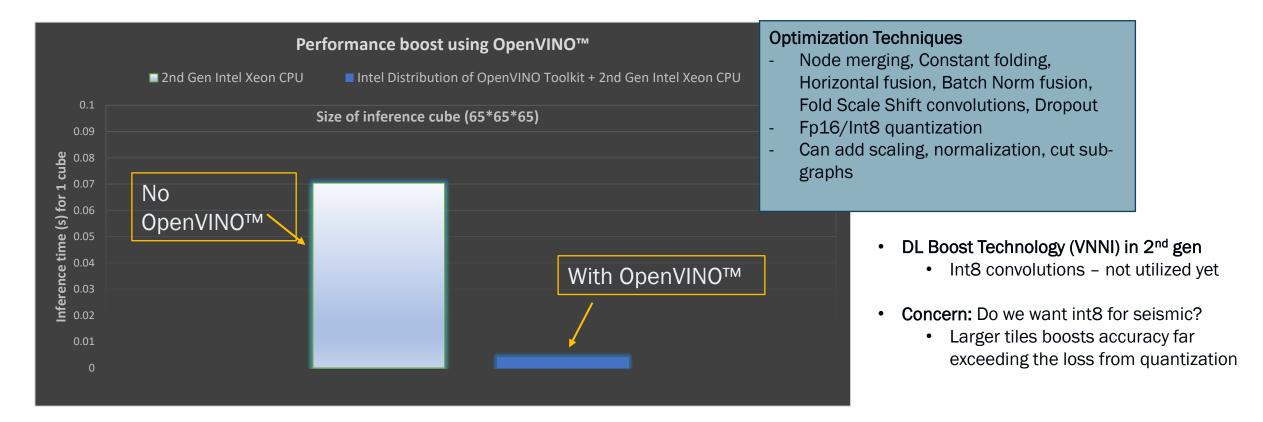
- Data used: 1 Gb 3D seismic data of F3 Dutch block
- OpenVino: 2019 R2 release (latest version)
- Python version: 3.6

- Py-torch version: 1.1.0
- Cuda version 9.90
- Complier : GCC 7.4.0
- OS: Ubuntu

Configurations and benchmark details can be found on Appendix 1. For more complete information about performance and benchmark results, visit www.intel.com/benchmarks. Performance results are based on testing as shown in configuration and may not reflect all publically available security updates. No product can be absolutely secure. See configuration disclosure for details. Optimization Notice: Intel's compilers may or may not optimize to the same degree for non-Intel microprocessors for optimizations that are not unique to Intel microprocessors. These optimizations include SSE2, SSE3, and SSSE3 instruction sets and other optimizations. Intel does not guarantee the availability, functionality, or effectiveness of any optimization on microprocessors not manufactured by Intel. Microprocessor-dependent optimizations in this product are intended for use with Intel microprocessors. Certain optimizations not specific to Intel microarchitecture are reserved for Intel microprocessors. Please refer to the applicable product User and Reference Guides for more information regarding the specific instruction sets covered by this notice.



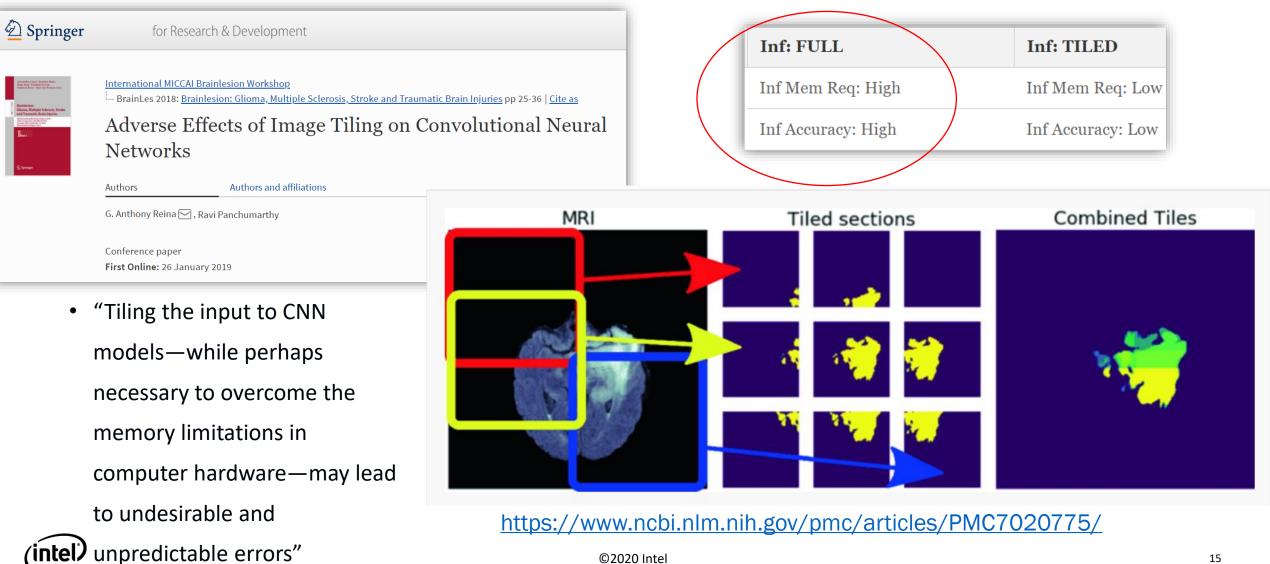




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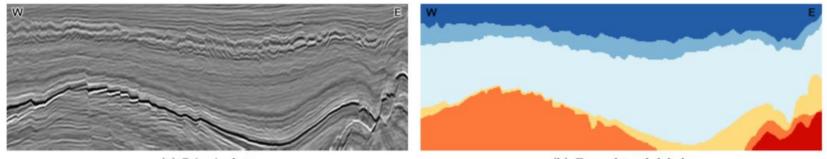
Intel R&D: Small V/S Large Tiles — Accuracy is Better With embedded Larger!



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Larger Seismic tile gives better definition for Inference

embedded VISION Summit



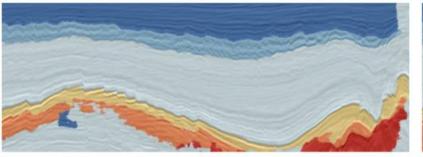
(a) Seismic data

(b) Ground truth labels

- Larger tiles boost accuracy
- Spatial context is imp in seismic

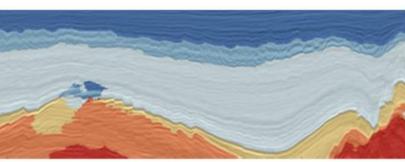
Research:

- Int8 performance on seismic: blog 3 in Resource slide
- Int8 on larger tiles! white paper coming



(g) Patch-based + aug + skip

https://arxiv.org/pdf/1901.07659.pdf



(h) Section-based + aug + skip

Metric	PA	Class Accuracy				MCA	FWIU			
Model		Zechstein	Scruff	Rijnland/Chalk	Lower N. S.	Middle N. S.	Upper N. S.	MCA	1 110	
Patch-based model	0.788	0.264	0.074	0.499	0.992	0.804	0.754	0.565	0.640	
Patch-based + aug.	0.852	0.434	0.221	0.707	0.974	0.884	0.916	0.689	0.743	
Patch-based + aug + skip	0.862	0.458	0.286	0.673	0.974	0.912	0.926	0.705	0.757	
Section-based model	0.879	0.219	0.539	0.744	0.951	0.872	0.973	0.716	0.789	
Section-based $+$ aug.	0.901	0.714	0.423	0.812	0.979	0.940	0.956	0.804	0.844	
Section-based $+$ aug $+$ skip	0.905	0.602	0.674	0.772	0.941	0.938	0.974	0.817	0.832	



Key Takeaway





The general-purpose 2nd generation Intel® Xeon® Scalable Processor together with Intel® Distribution of OpenVINO[™] toolkit provides DL performance that is well suited for Oil and Gas datasets



- ✓ Use OpenVINO[™] toolkit to boost inference performance for oil and gas datasets on Intel[®] Xeon[®] processor
- ✓ Int 8 quantization with larger tiles on 2nd generation Intel® Xeon® processor gives even better performance boost for seismic data – see blog 3 in Resources slide
- \checkmark Scale DL on existing CPUs that are used for HPC
- ✓ Use CPUs for other workloads when not doing DL



Resource Slide



Resources for OpenVINO™ toolkit

OpenVINO™ toolkit guide

Download OpenVINO[™] toolkit

Resource for Seismic

Seismic model used in this work

Blogs published on OpenVINO[™] toolkit + seismic Blog 1: Accelerating fault detection in 3D Seismic Blog 2: Accelerating seismic Interpretation using OpenVINO[™]

Blog 3: Lower Precision Pipeline for Seismic

Interpretation

2020 Embedded Vision Summit

Intel Booth



Workshops and demos to visit



General Session Speaker:

Bill Pearson, VP IOTG, GM Developer Enabling, Intel, Tuesday, September 15, 10:00 a.m. to 10:30 a.m. PDT: Streamline, Simplify and Solve for • the Edge of the Future

In-depth technical workshops

- Friday, September 18, 9:00 a.m. to 1:30 p.m. PDT: Using the Intel[®] Distribution of the OpenVINO[™] Toolkit for Deploying Accelerated Deep **Learning Applications**
- Monday, September 21, 9:00 a.m. to 1:30 p.m. PDT: Intel's Edge AI for Retail .
- Wednesday, September 23, 9:00 a.m. to 1:30 p.m. PDT: Intel's Edge AI for Industrial ٠

Technical presentations

- Alexander Kozlov, Deep Learning R&D engineer, Intel: Recent Advances in Post-Training Quantization ۰
- Dr. Manas Pathak, Global AI lead for oil and gas, Intel: Acceleration of Deep Learning for 3D Seismic .
- Tara K. Thimmanaik, solutions architect, Intel: Smarter Manufacturing Achieved with Intel's Deep Learning-Based Machine Vision .
- Gary Brown, Director of AI Marketing, Intel: Getting Efficient DL Inference Performance: Is It Really All About The TOPS? .
- Rama Karamsetty, Edge Al Marketing Manager, Intel: Edge Inferencing-- Scaling w/ Vision Accelerator Cards .
- Vaidyanathan Krishnamoorthy, edge inference solutions architect, Intel: Federated Edge Inferencing .

Dedicated demos and networking space Calgolux Foxconn IOTech MSKYLAB Thunder Soft XINJE



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